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EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE

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Abstract:

PROBLEM TO BE SOLVED: To obtain an epoxy resin composition for sealing a semiconductor which does not contain a halogen-containing flame-retardant and an antimony compound and is excellent in molding properties, flame retardancy, high temperature storage characteristics, moisture resistance reliability and solder crack resistance. **SOLUTION:** The epoxy resin composition for sealing a semiconductor comprises, as essential ingredients, (A) an epoxy resin, (B) a phenolic resin, (C) a curing accelerator, (D) an inorganic filler and (E) a metal hydroxide solid solution represented by the general formula: $Mg_{1-x}M_{2+x}(OH)_2$ (wherein M_{2+} is at least one divalent metal ion selected from the group consisting of Mn^{2+} , Fe^{2+} , Co^{2+} , Ni^{2+} , Cu^{2+} and Zn^{2+} ; and (x) is a number of $0.01 \leq x \leq 0.5$), and the specific surface area of the metal hydroxide solid solution represented by the general formula is 1.5-4.5 m²/g. **COPYRIGHT:** (C)2001,JPO

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